

**Elite Semiconductor Microelectronics Technology Inc.**

# Operating Updates

2024/03

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**ESMT** 晶豪科技

# Company Profile

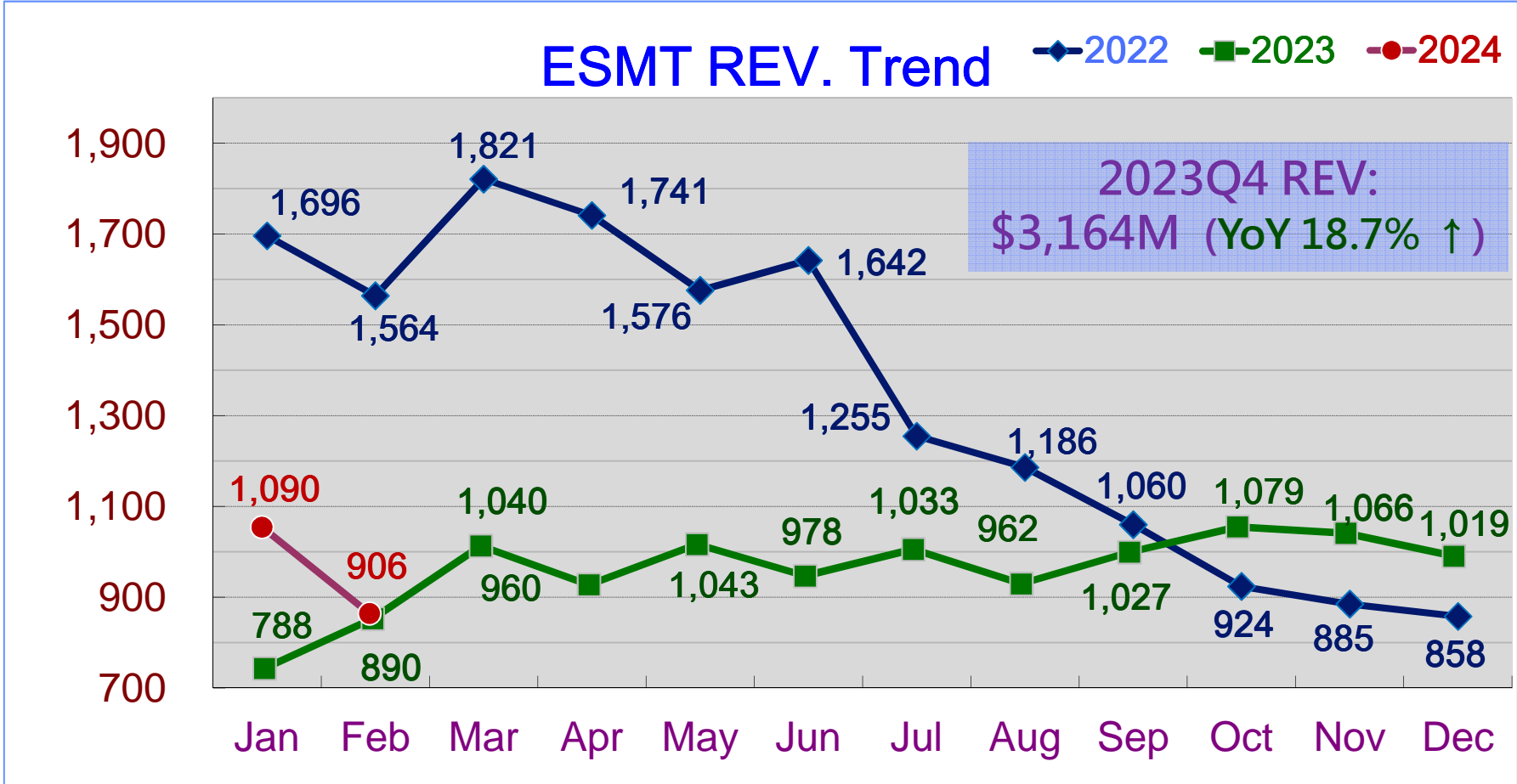
- Established in Jun, 1998
- Public Listed in TWSE : March 2002
- Merger: Advanic (2005/12), EON (2016/06)
- Location : Hsinchu Science Park, Taiwan
- Major Products :
  - Memory IC (DRAM/Flash/MCP/eMCP/eMMC)
  - Analog/Mixed Mode IC (Audio/Power/Motor Driver )
  - Wireless Solution for IoT
  - Sensor IC (Thermo/Photo)
- IC Design/Development, Manufacturing, Sales and related service

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# Consolidated Revenue

2022 \$16,208 M (32.03%↓)  
 2023 \$11,884 M (26.68%↓)



2023Q4 REV:  
 \$3,164M (YoY 18.7% ↑)

# Operating Updates

## Consolidated Income Statement

2023Q1~Q4

Unit : K \$NTD

Item	2023Q1	2023Q2	2023Q3	2023Q4	Q1'23~Q4'23 Total
Net Sales	2,717,377	2,980,731	3,021,539	3,164,474	11,884,121
Gross Margin(%)	5.88%	0.13%	2.38%	2.81%	2.73%
Operation Income	(372,828)	(473,472)	(378,989)	(413,263)	(1,638,552)
Rate(%)	(13.72%)	(15.88%)	(12.54%)	(13.06%)	(13.79%)
Non-operating income and exp.	3,997	370,780	234,024	(198,510)	410,291
Income before tax	(368,831)	(102,692)	(144,965)	(611,773)	(1,228,261)
Rate(%)	(13.57%)	(3.45%)	(4.80%)	(19.33%)	(10.34%)
Income after tax	(369,030)	(100,781)	(145,130)	(594,020)	(1,208,961)
EPS	(1.32)	(0.36)	(0.57)	(2.11)	(4.36)

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# Operating Updates

Consolidated Income Statement

2023Q1~Q4

Unit : K \$NTD

Item	2023Q4	2023Q3	QoQ	2022Q4	YoY
Net Sales	3,164,474	3,021,539	4.73%	2,666,777	18.66%
Gross Margin(%)	2.81%	2.38%		(22.63%)	
Operation Income	(413,263)	(378,989)	(9.04%)	(755,170)	45.28%
Rate(%)	(13.06%)	(12.54%)		(28.32%)	
Non-operating income and exp	(198,510)	234,024	(184.82%)	(393,327)	49.56%
Income before tax	(611,773)	(144,965)	(322.01%)	(1,148,497)	46.73%
Rate(%)	(19.33%)	(4.80%)		(43.07%)	
Income after tax	(594,020)	(145,130)	(309.30%)	(939,471)	36.77%
EPS	(2.11)	(0.57)		(3.35)	

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# 2023Q4 綜合損益表

## OP Income (QoQ)

Destocking, >> REV.↑ ,GM ↑ ,OP Income ↓

## Non-OP Income(QoQ)

(二十三)其他利益及損失

單位 新台幣仟元

## Impact of Foreign exchange

	112年4月1日至6月30日		112年7月1日至9月30日		112年度
處分不動產、廠房及設備	\$ 281,765	處分子公司投資利益	\$ -	處分子公司投資損失	\$ -
利益		租賃修改利益(損失)	16	處分不動產、廠房及設備	281,765
淨外幣兌換利益	84,109	淨外幣兌換利益	191,348	利益	
透過損益按公允價值衡量之		透過損益按公允價值衡量之		租賃修改利益	67
金融資產利益(損失)	5,796	金融資產利益(損失)	(8,118)	淨外幣兌換利益	12,043
什項支出	(42,259)	虧損性合約損失	-	透過損益按公允價值衡量之	
	\$ 329,411	什項支出	(698)	金融資產利益(損失)	9,172
			\$ 182,548	虧損性合約損失	-
				什項支出	(43,902)
					\$ 259,145

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# Operating Updates

## Consolidated Balance Sheet

2023Q4

Unit : K \$NTD

<b>Assets</b>	<b>2023/12/31</b>	<b>2023/9/30</b>	<b>2023/6/30</b>	<b>2022/12/31</b>
Cash and cash equivalents	\$4,520,314	\$4,901,815	\$4,936,651	\$4,764,681
Accounts receivable, net	1,204,521	1,345,298	1,257,073	962,383
Inventories	6,885,637	7,661,918	7,717,758	8,369,225
<b>Total current assets</b>	<b>13,552,324</b>	<b>15,844,793</b>	<b>15,795,665</b>	<b>15,052,131</b>
<b>Total non-current assets</b>	<b>4,544,886</b>	<b>3,726,396</b>	<b>3,805,887</b>	<b>4,673,598</b>
<b>Total assets</b>	<b>18,097,210</b>	<b>19,571,189</b>	<b>19,601,552</b>	<b>19,725,729</b>

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# Operating Updates

## Consolidated Balance Sheet

2023Q4

Unit : K \$NTD

Liab.& Equity.	2023/12/31	2023/9/30	2023/6/30	2022/12/31
Short-term borrowings	\$2,620,000	\$3,720,000	\$3,440,000	\$3,175,000
Accounts payable	2,282,490	2,867,679	2,332,952	2,325,661
Other payables	714,823	1,111,597	2,031,248	1,426,556
<b>Total current liabilities</b>	<b>6,181,882</b>	<b>8,473,150</b>	<b>8,396,813</b>	<b>7,492,375</b>
Bonds payable	942,923			
Long-term borrowings	643,400	643,400	643,400	643,400
<b>Total non-current liabilities</b>	<b>1,995,236</b>	<b>822,516</b>	<b>795,667</b>	<b>795,478</b>
<b>Total liabilities</b>	<b>8,177,118</b>	<b>9,295,666</b>	<b>9,192,480</b>	<b>8,287,853</b>
<b>Total equity</b>	<b>9,920,092</b>	<b>10,275,523</b>	<b>10,409,072</b>	<b>11,437,876</b>
<b>Total liabilities and equity</b>	<b>18,097,210</b>	<b>19,571,189</b>	<b>19,601,552</b>	<b>19,725,729</b>



# Review & Outlook

1. Lift rates may stopped by FED and ECB due to inflation slowing down.
2. Demand of HBM and conversion of DDR4 to DDR5 will help destocking of niche product market.
3. Price rebound, started from Q4'23, is likely to continue in 2024
4. Global market recovery exposed to geopolitical tension , Russia-Ukraine conflict and the US-China conflict
5. Rapid growth of demand of EV/Automotive Electronics  
→ ESMT ISO 26262 certified

Thank you

Q & A